Product / Package Information

Package	LFCSP - Punch
Body Size (mm)	5 X 5 X 0.85 (3.1 EP)
LeadCount	32
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.67E-02	86.9	869100	32.14	321426
Thermosets	Epoxy & Phenol Resin	Proprietary	3.93E-03	12.8	127800	4.73	47265
Other inorganic materials	Carbon black	1333-86-4	9.53E-05	0.3	3100	0.11	1146
Subtotal			3.07 E-02	100.00	1000000	36.98	369837

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.40 E-02	97.5	975000	52.89	528899
Copper & its alloys	Iron	7439-89-6	1.06 E-03	2.35	23500	1.27	12748
Copper & its alloys	Zinc	7440-66-6	5.41 E-05	0.12	1200	0.07	651
Copper & its alloys	Phosphorus	7723-14-0	1.35 E-05	0.03	300	0.02	163
Subtotal			4.51 E-02	100.00	1000000	54.25	542460

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.03 E-05	100.0	1000000	0.11	1087

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.05 E-03	100.0	1000000	1.26	12629

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.14 E-04	100.0	1000000	0.26	2575

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.11 E-03	100.0	1000000	6.15	61534

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.02 E-04	73.40	734000	0.73	7250
Thermoset	Epoxy Resin	Proprietary	1.51 E-04	18.35	183500	0.18	1813
Other inorganic materials	Metal oxide	Proprietary	2.26 E-05	2.75	27500	0.03	272
Others	Curing and hardening agent	Proprietary	2.26 E-05	2.75	27500	0.03	272
Other organic materials	Gamma Butyrolactone	96-48-0	2.26 E-05	2.75	27500	0.03	272
Subtotal			8.21 E-04	100.0	1000000	0.99	9878

	Weight (g)	Percentage (%)	PPM
Package Totals	**8.31 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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